

Title (en)

SAWING AND HANDLER SYSTEM FOR MANUFACTURING SEMICONDUCTOR PACKAGE

Title (de)

SÄGE- UND HANDHABUNGSSYSTEM FÜR DIE HERSTELLUNG EINES HALBLEITERGEHÄUSES

Title (fr)

SYSTEME DE SCIAGE ET DE TRAITEMENT POUR LA FABRICATION D'UN BOITIER A SEMI-CONDUCTEURS

Publication

**EP 1743368 A1 20070117 (EN)**

Application

**EP 04821957 A 20041130**

Priority

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- KR 20040032326 A 20040507

Abstract (en)

[origin: WO2005109492A1] Disclosed is a sawing and handler system for manufacturing a semiconductor package. The system includes an on-loader unit, a sawing machine and a cleaning unit, which are sequentially aligned in the system so that the semiconductor strip or the semiconductor package sequentially passes through the on-loader unit, the sawing machine and the cleaning unit according to a process order thereof, thereby improving the sawing and processing speed of the system for the semiconductor strip.

IPC 8 full level

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CPC (source: EP)

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